


PCN Number:	20190206000.0	PCN Date:	February 11, 2019
Title:	Datasheet for TMP1075		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process
Notification Details			
Description of Change:			
<p>Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.</p>			
		TMP1075 <small>SBOS854C – MARCH 2018 – REVISED JANUARY 2019</small>	
Changes from Revision B (December 2018) to Revision C			
			Page
•	Changed TMP1075DSG package moved from Preview to Production Data		1
•	Changed min/max limit from 1.5°C to 1°C in the <i>Temperature Accuracy (DGK & D)</i> graph		1
•	Changed min/max limit from 1.5°C to 1°C in the <i>DGK & D Temperature Error vs Temperature</i> graph		7
•	Added <i>DSG Temperature Error vs Temperature</i> graph		7
Changes from Revision A (June 2018) to Revision B			
			Page
•	Added TMP1075DSG package		1
•	Updated description section of the data sheet and added a <i>Description (continued)</i> section		1
•	Changed names from CR1 and CR0 to R1 and R0		5
•	Added TMP1075 Configuration register support for single byte read and write		19
•	Added Software support section for migrating from xx75 to TMP1075		22
The datasheet number will be changing.			
Device Family	Change From:	Change To:	
TMP1075	SBOS854A	SBOS854C	
These changes may be reviewed at the datasheet links provided.			
http://www.ti.com/product/TMP1075			
Reason for Change:			
To accurately reflect device characteristics.			
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):			
No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.			
Changes to product identification resulting from this PCN:			
None.			
Product Affected:			
TMP1075DGKR	TMP1075DGKT	TMP1075DR	TMP1075DSGR
TMP1075DSGT			

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
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